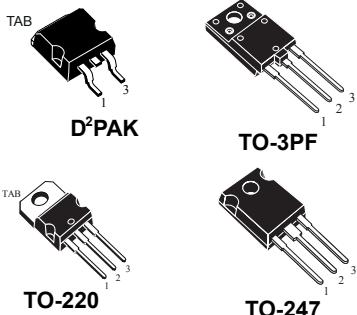


## Trench gate field-stop IGBT, V series 600 V, 40 A very high speed



### Features

- Maximum junction temperature:  $T_J = 175 \text{ }^{\circ}\text{C}$
- Tail-less switching off
- $V_{CE(\text{sat})} = 1.8 \text{ V (typ.)} @ I_C = 40 \text{ A}$
- Tight parameters distribution
- Safe paralleling
- Low thermal resistance

### Applications

- Welding
- Power factor correction
- UPS
- Solar inverters
- Chargers

### Description

These devices are IGBTs developed using an advanced proprietary trench gate field-stop structure. These devices are part of the V series IGBTs, which represent an optimum compromise between conduction and switching losses to maximize the efficiency of very high frequency converters. Furthermore, the positive  $V_{CE(\text{sat})}$  temperature coefficient and very tight parameter distribution result in safer paralleling operation.



Product status links
<a href="#">STGB40V60F</a>
<a href="#">STGFW40V60F</a>
<a href="#">STGP40V60F</a>
<a href="#">STGW40V60F</a>

## 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value		Unit
		D <sup>2</sup> PAK, TO-247, TO-3P	TO-3PF	
V <sub>CES</sub>	Collector-emitter voltage ( $V_{GE} = 0$ V)	600		V
I <sub>C</sub>	Continuous collector current at $T_C = 25$ °C	80		A
	Continuous collector current at $T_C = 100$ °C	40		A
I <sub>CP</sub> <sup>(1)</sup>	Pulsed collector current	160		A
V <sub>GE</sub>	Gate-emitter voltage	±20		V
P <sub>TOT</sub>	Total power dissipation at $T_C = 25$ °C	283	98.5	W
V <sub>ISO</sub>	Insulation withstand voltage (RMS) from all three leads to external heat sink ( $t = 1$ s; $T_C = 25$ °C)		3.5	kV
T <sub>stg</sub>	Storage temperature range	-55 to 150		°C
T <sub>J</sub>	Operating junction temperature range	-55 to 175		°C

1. Pulse width is limited by maximum junction temperature.

**Table 2. Thermal data**

Symbol	Parameter	Value		Unit
		TO-247, TO-3P	TO-3PF	
R <sub>thJC</sub>	Thermal resistance, junction-to-case	0.53	1.52	°C/W
R <sub>thJA</sub>	Thermal resistance, junction-to-ambient	50		°C/W

## 2 Electrical characteristics

$T_J = 25^\circ\text{C}$  unless otherwise specified

Table 3. Static characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{CES}}$	Collector-emitter breakdown voltage	$V_{GE} = 0 \text{ V}, I_C = 2 \text{ mA}$	600			V
$V_{CE(\text{sat})}$	Collector-emitter saturation voltage	$V_{GE} = 15 \text{ V}, I_C = 40 \text{ A}$		1.8	2.3	V
		$V_{GE} = 15 \text{ V}, I_C = 40 \text{ A}, T_J = 125^\circ\text{C}$		2.15		
		$V_{GE} = 15 \text{ V}, I_C = 40 \text{ A}, T_J = 175^\circ\text{C}$		2.35		
$V_{GE(\text{th})}$	Gate threshold voltage	$V_{CE} = V_{GE}, I_C = 1 \text{ mA}$	5	6	7	V
$I_{CES}$	Collector cut-off current	$V_{GE} = 0 \text{ V}, V_{CE} = 600 \text{ V}$			25	$\mu\text{A}$
$I_{GES}$	Gate-emitter leakage current	$V_{CE} = 0 \text{ V}, V_{GE} = \pm 20 \text{ V}$			$\pm 250$	nA

Table 4. Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{ies}$	Input capacitance	$V_{CE} = 25 \text{ V}, f = 1 \text{ MHz}, V_{GE} = 0 \text{ V}$	-	5400	-	pF
$C_{oes}$	Output capacitance		-	220	-	pF
$C_{res}$	Reverse transfer capacitance		-	180	-	pF
$Q_g$	Total gate charge	$V_{CC} = 480 \text{ V}, I_C = 40 \text{ A}, V_{GE} = 0 \text{ to } 15 \text{ V}$ (see Figure 28. Gate charge test circuit)	-	226	-	nC
$Q_{ge}$	Gate-emitter charge		-	38	-	nC
$Q_{gc}$	Gate-collector charge		-	95	-	nC

**Table 5. Switching characteristics (inductive load)**

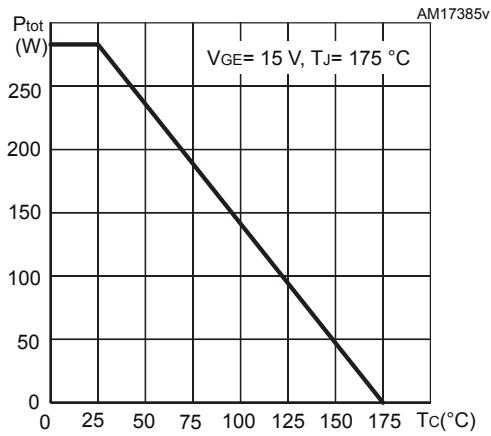
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400 \text{ V}, I_C = 40 \text{ A},$ $R_G = 10 \Omega, V_{GE} = 15 \text{ V}$ (see Figure 27. Test circuit for inductive load switching)	-	52	-	ns
$t_r$	Current rise time		-	17	-	ns
$(di/dt)_{on}$	Turn-on current slope		-	1850	-	A/ $\mu$ s
$t_{d(off)}$	Turn-off delay time		-	208	-	ns
$t_f$	Current fall time		-	20	-	ns
$E_{on}^{(1)}$	Turn-on switching energy		-	456	-	$\mu$ J
$E_{off}^{(2)}$	Turn-off switching energy		-	411	-	$\mu$ J
$E_{ts}$	Total switching energy		-	867	-	$\mu$ J
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400 \text{ V}, I_C = 40 \text{ A},$ $R_G = 10 \Omega, V_{GE} = 15 \text{ V}, T_J = 175 \text{ }^\circ\text{C}$ (see Figure 27. Test circuit for inductive load switching)	-	52	-	ns
$t_r$	Current rise time		-	21	-	ns
$(di/dt)_{on}$	Turn-on current slope		-	1538	-	A/ $\mu$ s
$t_{d(off)}$	Turn-off-delay time		-	220	-	ns
$t_f$	Current fall time		-	21	-	ns
$E_{on}^{(1)}$	Turn-on switching energy		-	1330	-	$\mu$ J
$E_{off}^{(2)}$	Turn-off switching energy		-	560	-	$\mu$ J
$E_{ts}$	Total switching energy		-	1890	-	$\mu$ J

1. Including the reverse recovery of the external diode. The diode is the same of the co-packed STGW40V60DF.

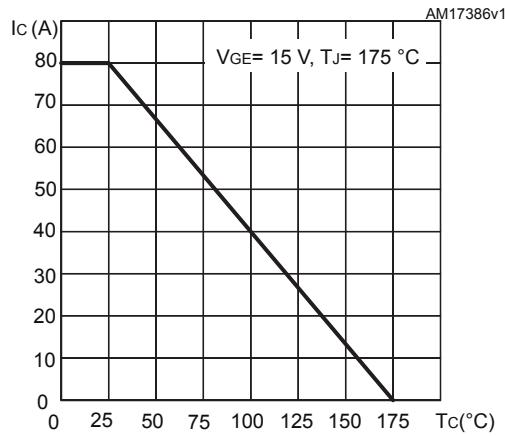
2. Including the tail of the collector current.

## 2.1 Electrical characteristics (curves)

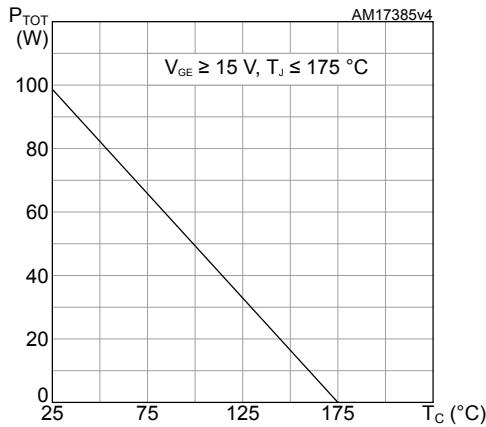
**Figure 1. Power dissipation vs case temperature for D<sup>2</sup>PAK, TO-247 and TO-3P**



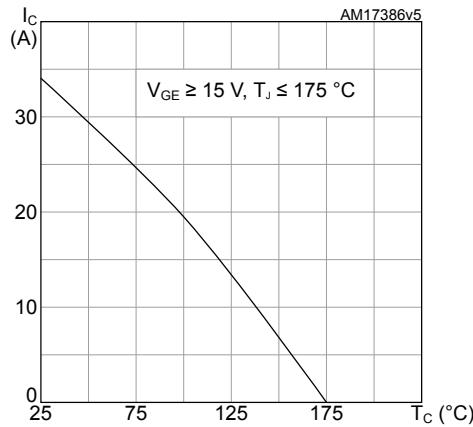
**Figure 2. Collector current vs case temperature for D<sup>2</sup>PAK, TO-247 and TO-3P**



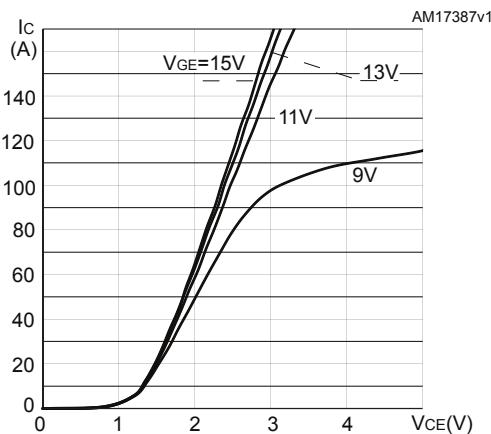
**Figure 3. Power dissipation vs case temperature for TO-3PF**



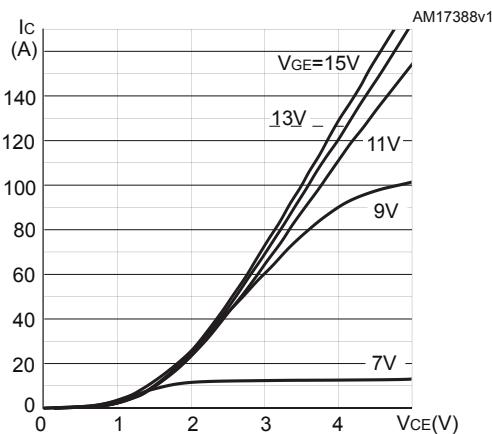
**Figure 4. Collector current vs case temperature for TO-3PF**

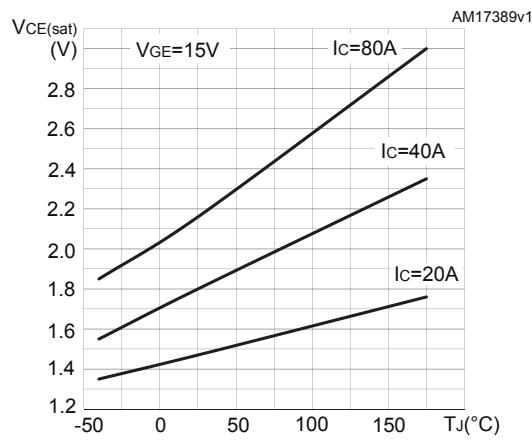
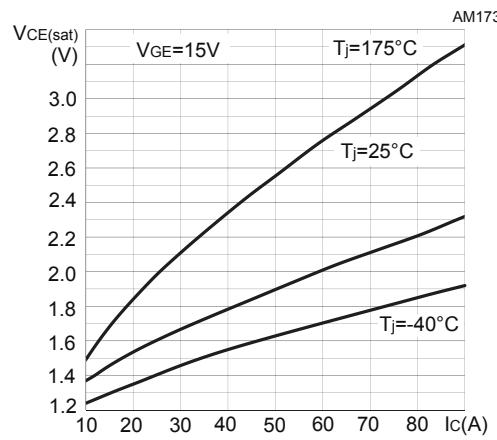
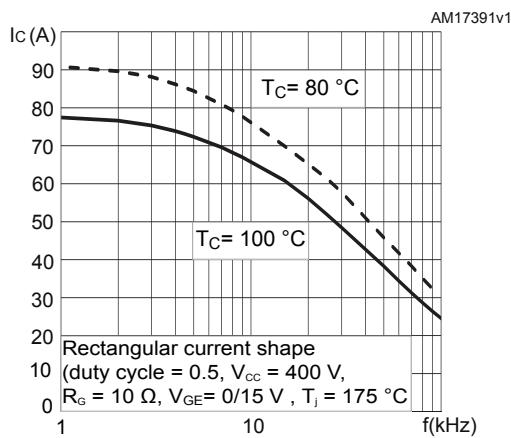
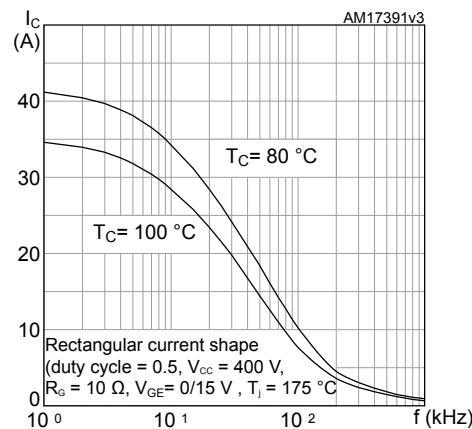
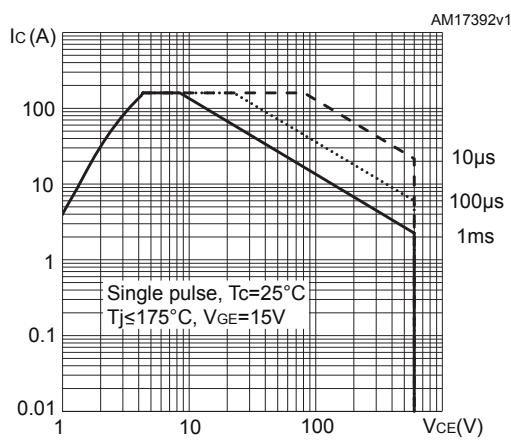
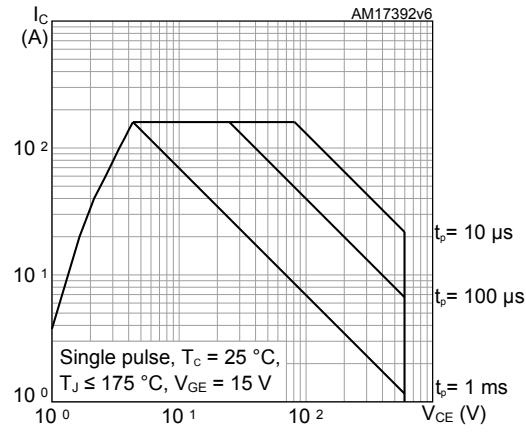


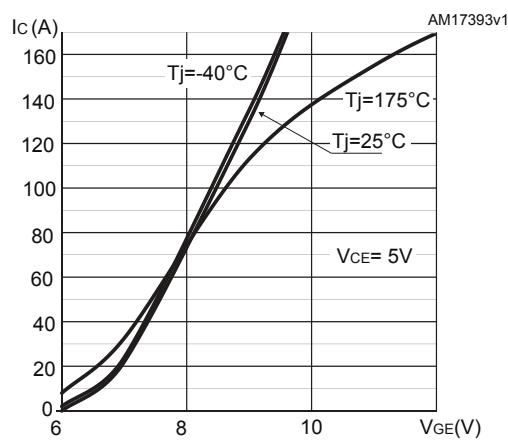
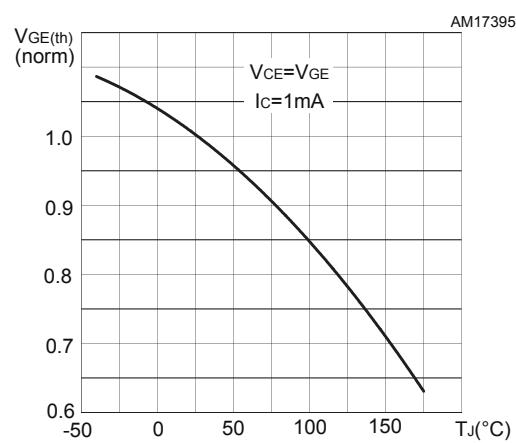
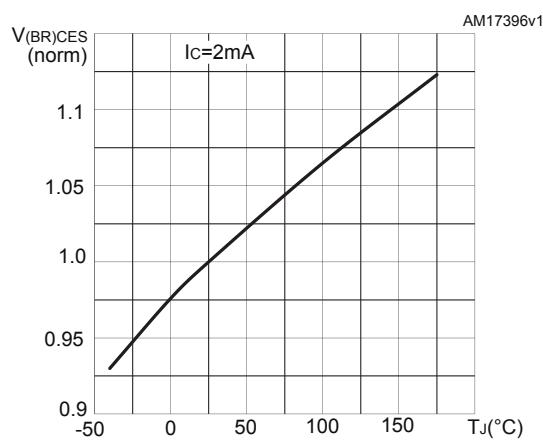
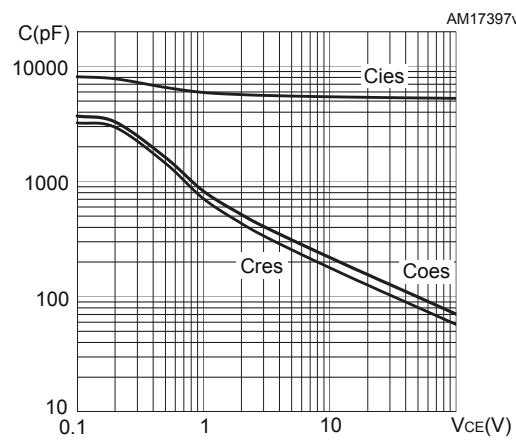
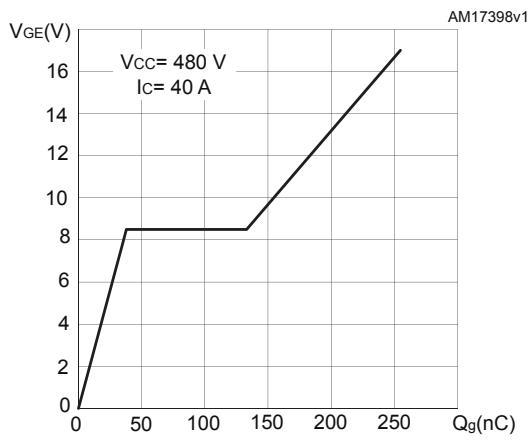
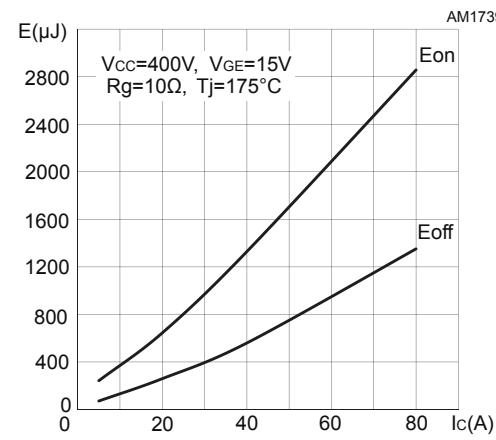
**Figure 5. Output characteristics ( $T_J = 25^\circ\text{C}$ )**



**Figure 6. Output characteristics ( $T_J = 175^\circ\text{C}$ )**



**Figure 7.  $V_{CE(sat)}$  vs junction temperature**

**Figure 8.  $V_{CE(sat)}$  vs collector current**

**Figure 9. Collector current vs switching frequency for D<sup>2</sup>PAK, TO-247 and TO-3P**

**Figure 10. Collector current vs switching frequency for TO-3PF**

**Figure 11. Forward bias safe operating area for D<sup>2</sup>PAK, TO-247 and TO-3P**

**Figure 12. Forward bias safe operating area for TO-3PF**


**Figure 13. Transfer characteristics**

**Figure 14. Normalized  $V_{GE(th)}$  vs junction temperature**

**Figure 15. Normalized  $V_{(BR)CES}$  vs junction temperature**

**Figure 16. Capacitance variations**

**Figure 17. Gate charge vs gate-emitter voltage**

**Figure 18. Switching energy vs collector current**


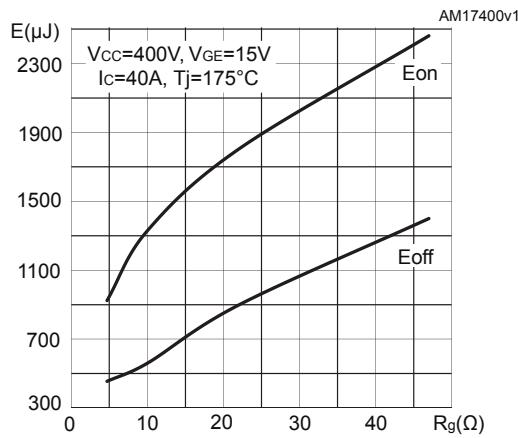
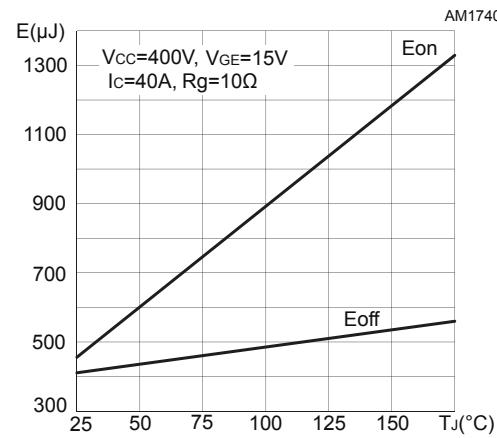
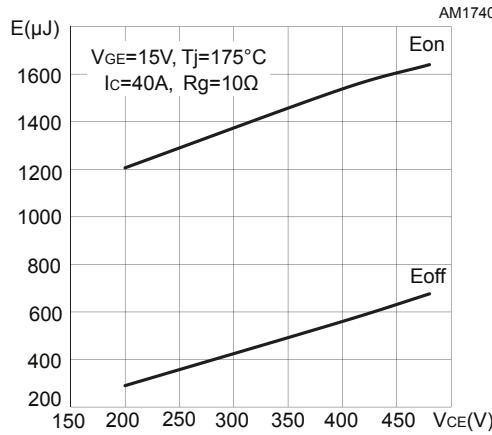
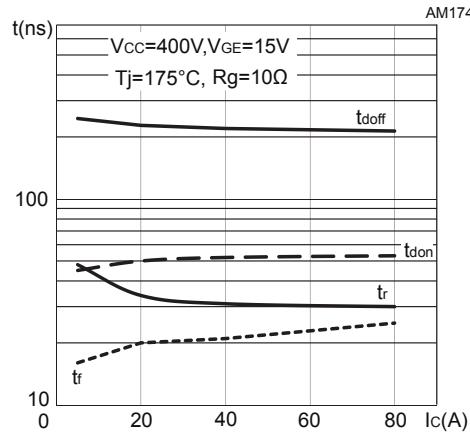
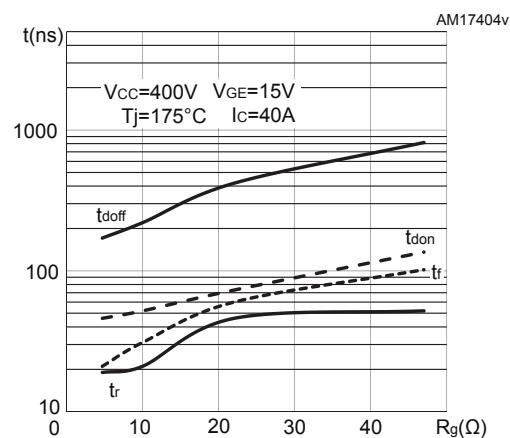
**Figure 19. Switching energy vs gate resistance**

**Figure 20. Switching energy vs junction temperature**

**Figure 21. Switching energy vs collector emitter voltage**

**Figure 22. Switching times vs collector current**

**Figure 23. Switching times vs gate resistance**


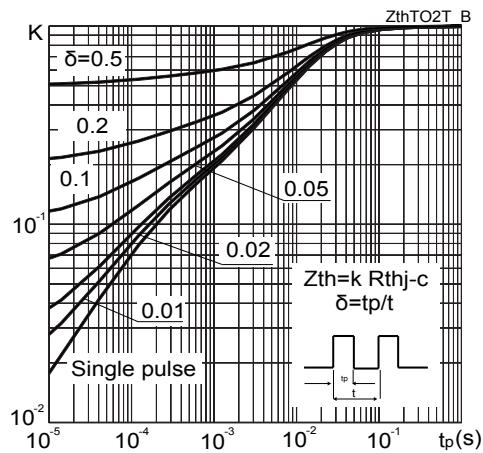
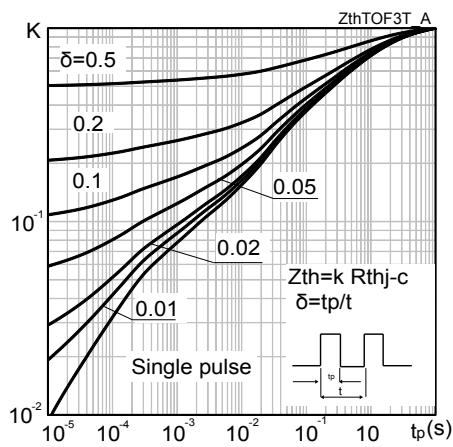
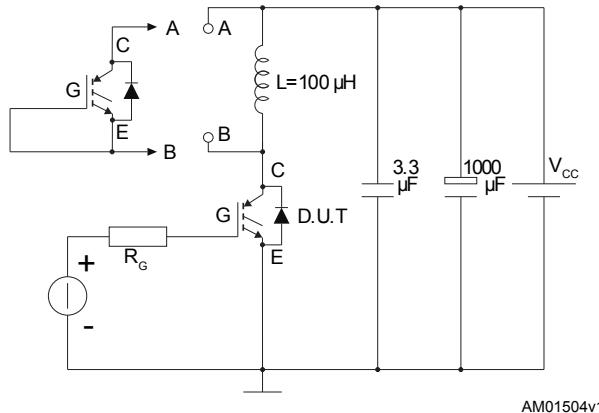
Figure 24. Thermal impedance for D<sup>2</sup>PAK, TO-247 and TO-3P

Figure 25. Thermal impedance for TO-3PF



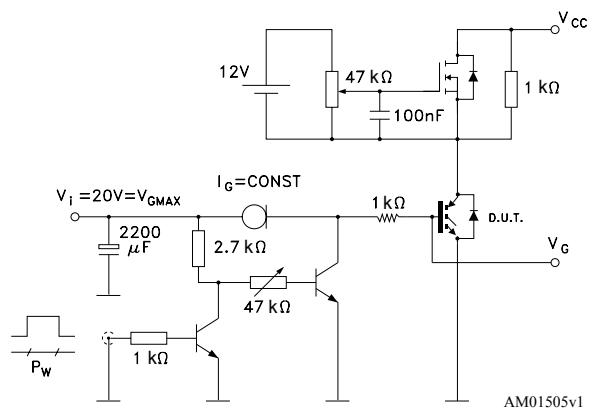
### 3 Test circuits

**Figure 26. Test circuit for inductive load switching**



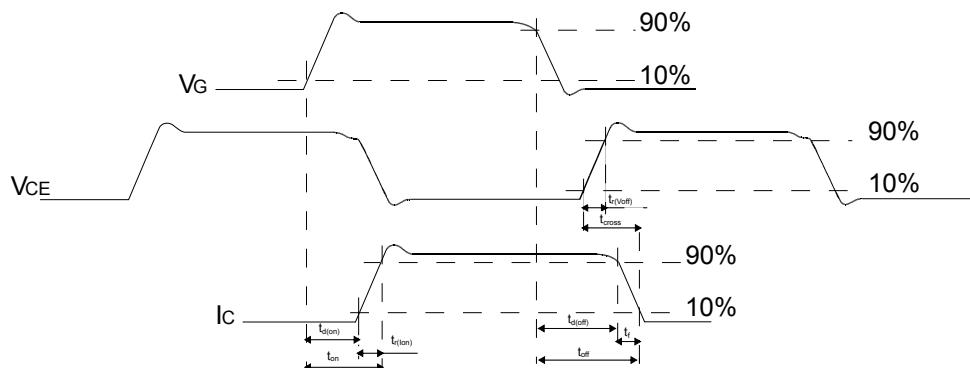
AM01504v1

**Figure 27. Gate charge test circuit**



AM01505v1

**Figure 28. Switching waveform**



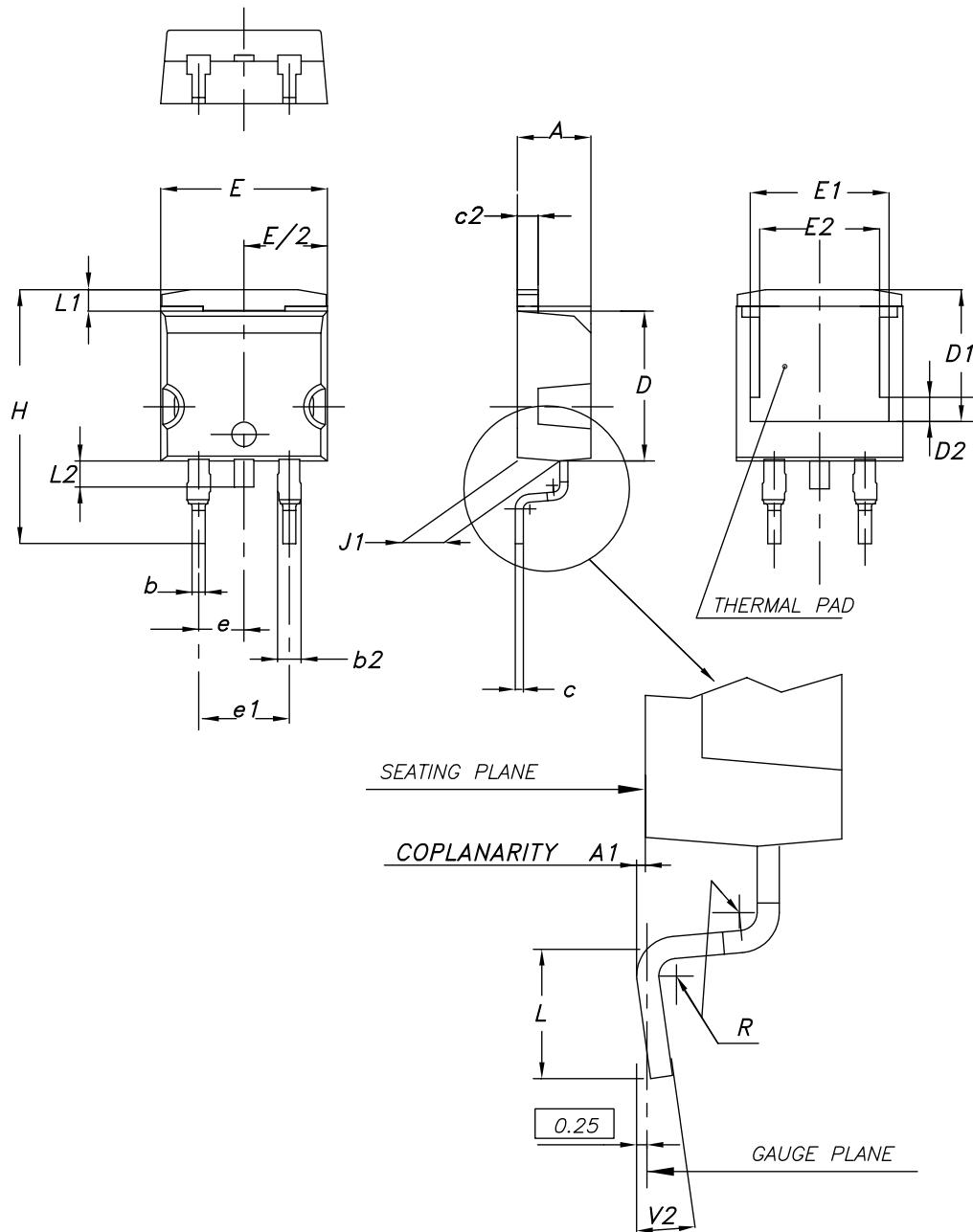
AM01506v1

## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 4.1 D<sup>2</sup>PAK (TO-263) type A2 package information

Figure 29. D<sup>2</sup>PAK (TO-263) type A2 package outline

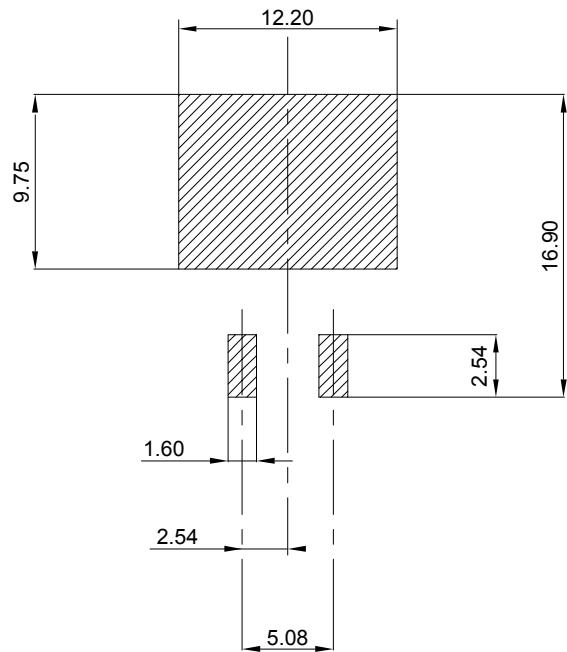


0079457\_A2\_26

**Table 6.** D<sup>2</sup>PAK (TO-263) type A2 package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10.00		10.40
E1	8.70	8.90	9.10
E2	7.30	7.50	7.70
e		2.54	
e1	4.88		5.28
H	15.00		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.40	
V2	0°		8°

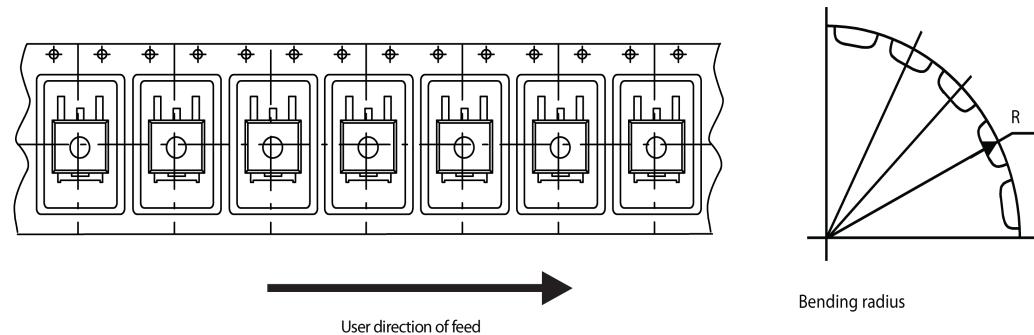
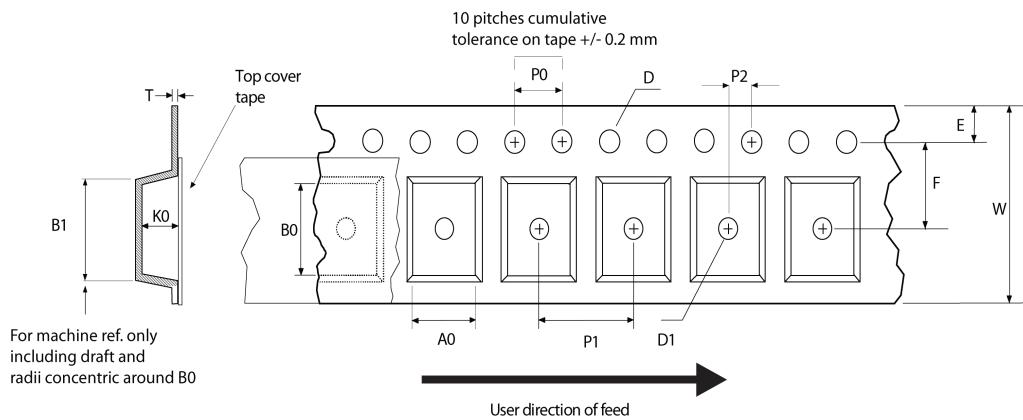
Figure 30. D<sup>2</sup>PAK (TO-263) recommended footprint (dimensions are in mm)



Footprint\_26

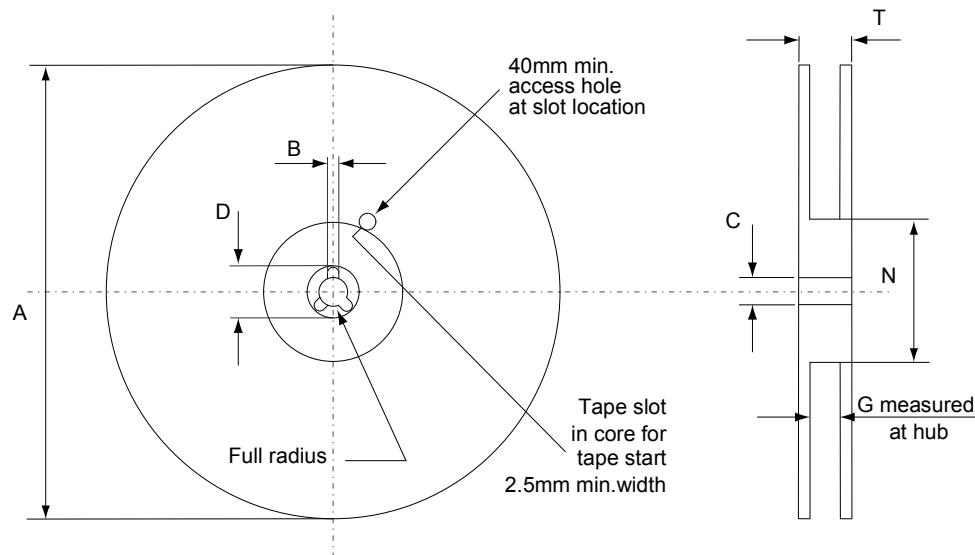
#### 4.1.1 D<sup>2</sup>PAK packing information

Figure 31. D<sup>2</sup>PAK tape outline



Bending radius

AM08852v1

Figure 32. D<sup>2</sup>PAK reel outline


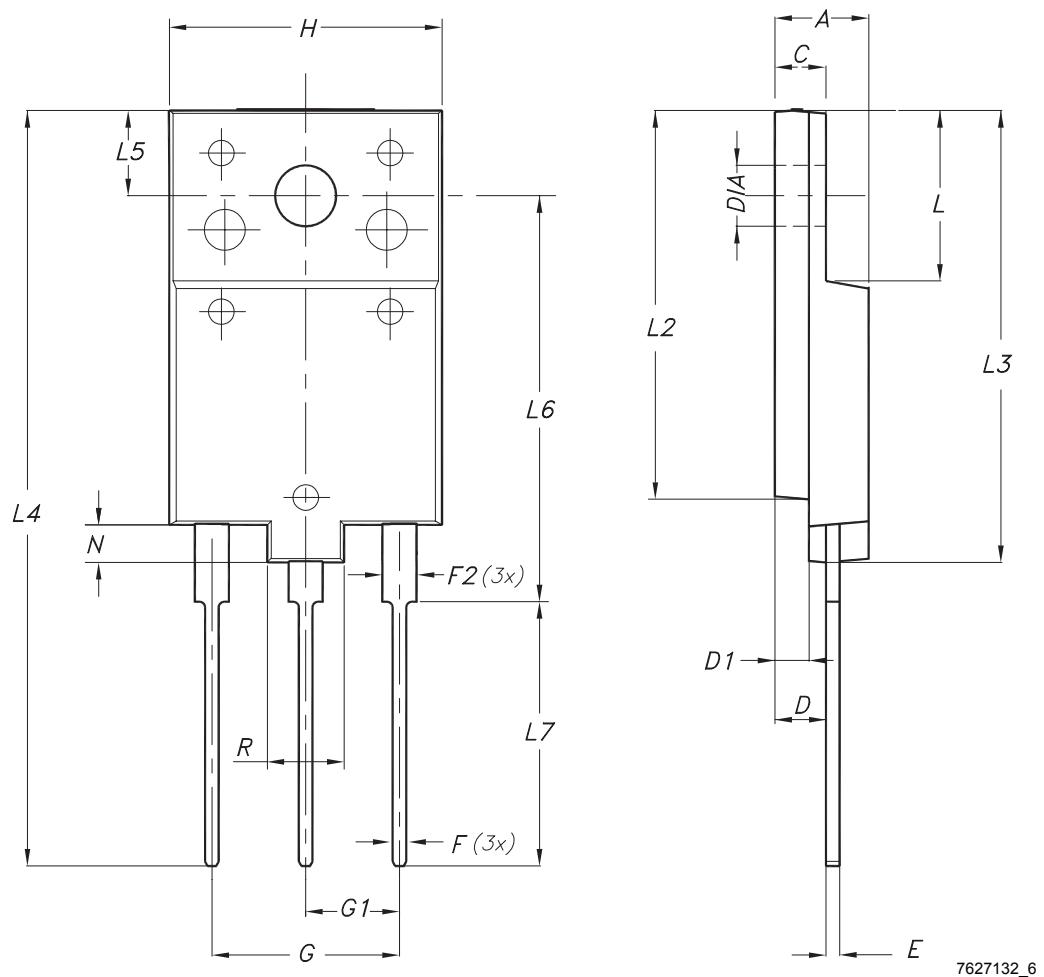
AM06038v1

Table 7. D<sup>2</sup>PAK tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1	Base quantity		1000
P2	1.9	2.1	Bulk quantity		1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

## 4.2 TO-3PF package information

Figure 33. TO-3PF package outline

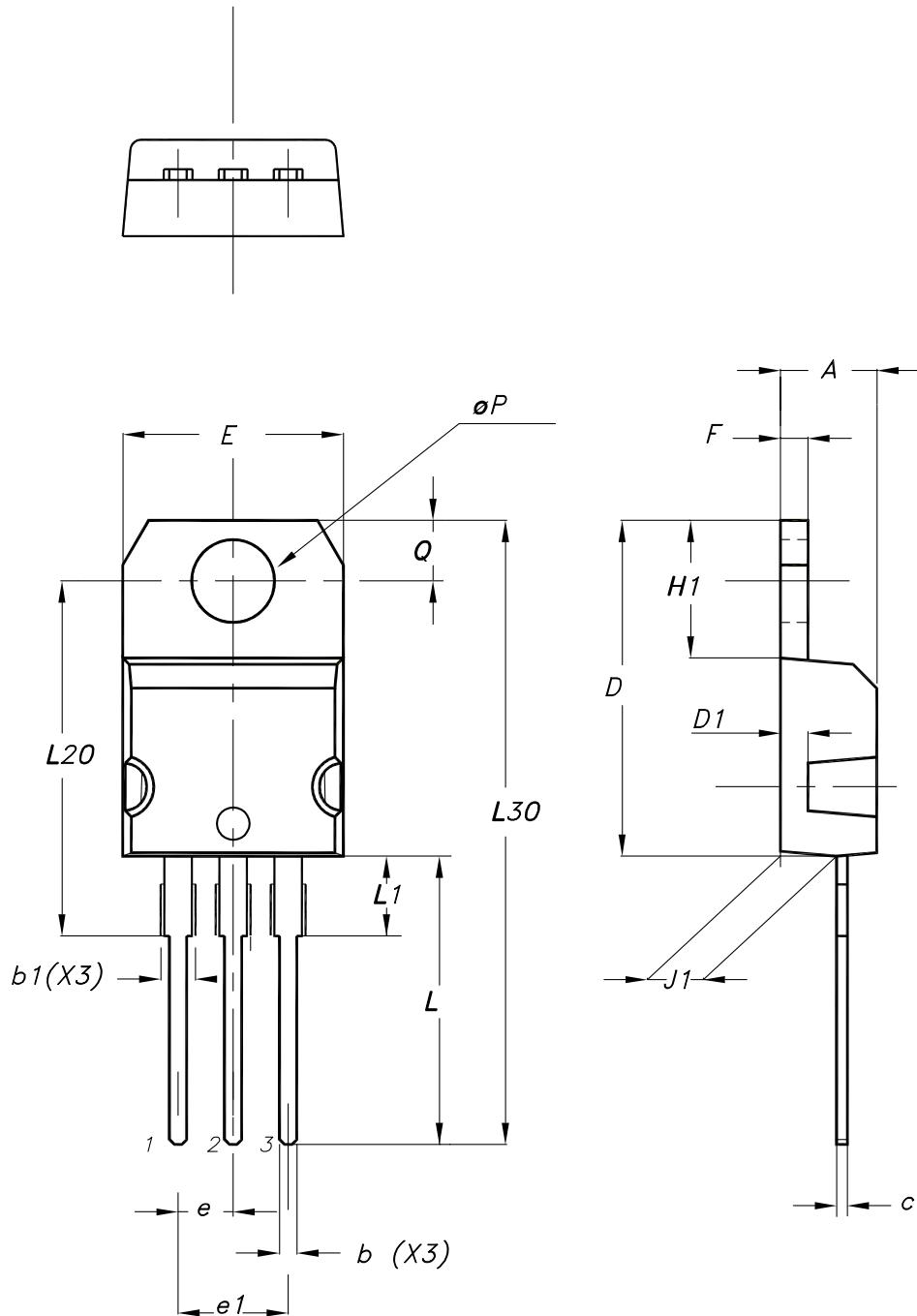


**Table 8. TO-3PF mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	5.30		5.70
C	2.80		3.20
D	3.10		3.50
D1	1.80		2.20
E	0.80		1.10
F	0.65		0.95
F2	1.80		2.20
G	10.30		11.50
G1		5.45	
H	15.30		15.70
L	9.80	10.00	10.20
L2	22.80		23.20
L3	26.30		26.70
L4	43.20		44.40
L5	4.30		4.70
L6	24.30		24.70
L7	14.60		15.00
N	1.80		2.20
R	3.80		4.20
Dia	3.40		3.80

#### 4.3 TO-220 type A package information

Figure 34. TO-220 type A package outline



0015988\_typeA\_Rev\_23

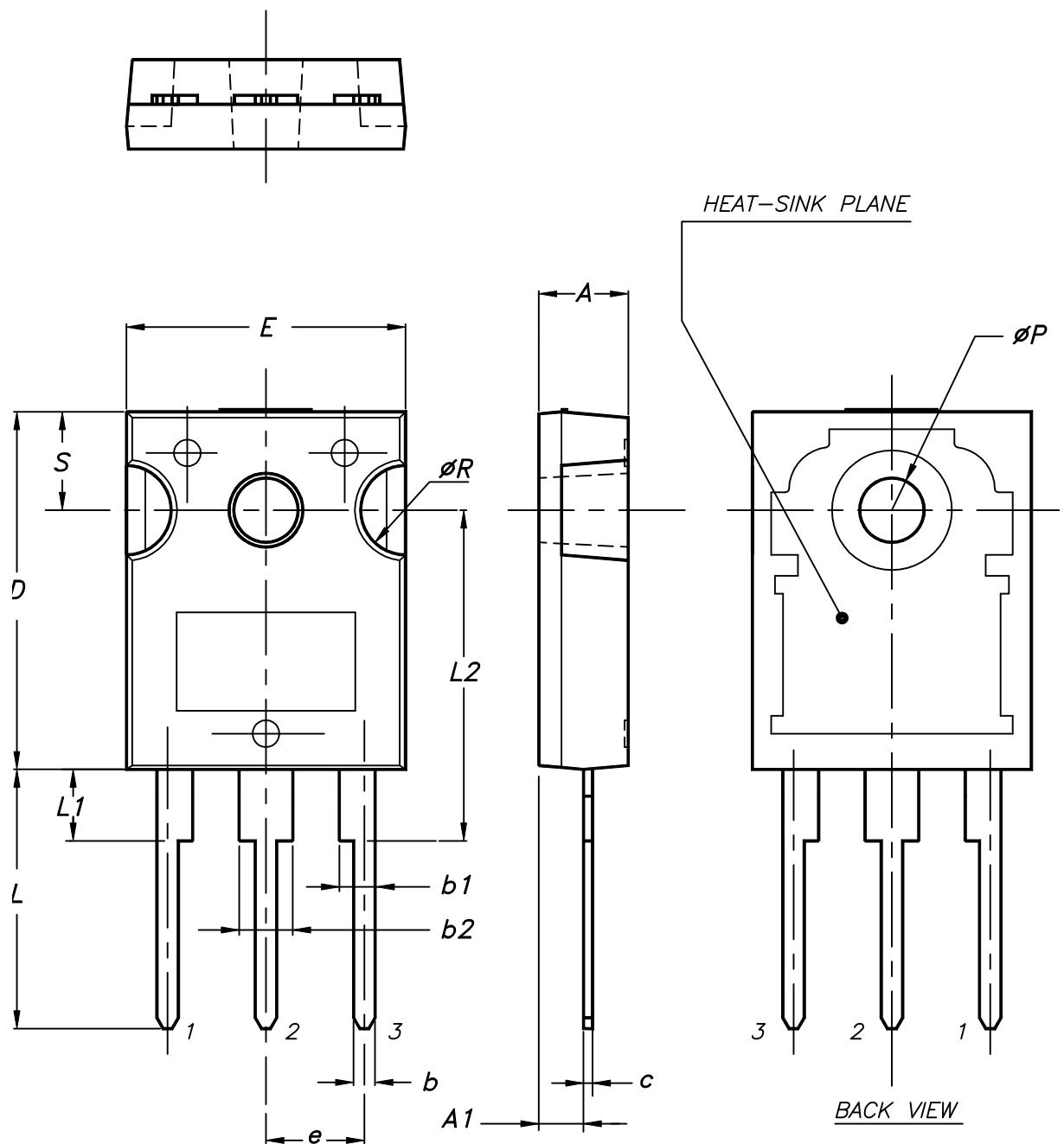


Table 9. TO-220 type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95
Slug flatness		0.03	0.10

#### 4.4 TO-247 package information

Figure 35. TO-247 package outline



0075325\_9

Table 10. TO-247 package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

## 5 Ordering information

**Table 11. Order codes**

Order code	Marking	Package	Packing
STGB40V60F	GB40V60F	D <sup>2</sup> PAK	Tape and reel
STGFW40V60F	GFW40V60F	TO-3PF	
STGP40V60F	GP40V60F	TO-220	Tube
STGW40V60F	GW40V60F	TO-247	

## Revision history

**Table 12. Document revision history**

Date	Revision	Changes
04-Jun-2013	1	Initial release
23-Apr-2014	2	<p>Updated title, features and description in cover page.</p> <p>Added new device in TO-3PF.</p> <p>Updated <i>Table 1: Device summary</i>, <i>Table 2: Absolute maximum ratings</i> <i>Table 3: Thermal data</i> and <i>Section 4: Package mechanical data</i>.</p> <p>Added <i>Figure 4: Power dissipation vs. case temperature for TO-3PF</i>, <i>Figure 5: Collector current vs. case temperature for TO-3PF</i>, <i>Figure 11: Collector current vs. switching frequency for TO-3PF</i> and <i>Figure 12: Forward bias safe operating area for D2PAK, TO-247 and TO-3P</i>.</p> <p>Minor text changes.</p>
04-Mar-2021	3	<p>Modified application section on cover page.</p> <p>Modified <i>Table 1. Absolute maximum ratings</i>, <i>Table 2. Thermal data</i>.</p> <p>Modified <i>Figure 4. Power dissipation vs case temperature for TO-3PF</i>, <i>Figure 5. Collector current vs case temperature for TO-3PF</i>, <i>Figure 11. Collector current vs switching frequency for TO-3PF</i> and <i>Figure 13. Forward bias safe operating area for TO-3PF</i>.</p>

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